

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L23	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (distributed adj simulat\$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L22	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L21	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L20	29	(US-20040078319-\$ or US-20050016947-\$ or US-20030078738-\$ or US-20040102934-\$ or US-20030101251-\$ or US-20050010319-\$ or US-20020107604-\$).did. or (US-6774998-\$ or US-6757645-\$ or US-6643616-\$ or US-6763277-\$ or US-6571371-\$ or US-6728591-\$ or US-6812045-\$ or US-6628809-\$ or US-6905895-\$ or US-7333871-\$ or US-6810296-\$ or US-	US-PGPUB; USPAT	OR	ON	2011/05/07 15:12

		5583780-\$ or US- 6304834-\$ or US- 7055112-\$ or US- 6587744-\$ or US- 7184850-\$ or US- 7356377-\$ or US- 6560503-\$ or US- 5526293-\$ or US- 7622308-\$).did. or (US-5866437-\$ or US- 20040078319-\$ or WO-200277589-\$ or US-20050010319-\$ or WO-200177979-\$ or US-20030135302-\$ or JP-2007172210-\$). did.				
L18	922	703/7.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:09
L17	26	438/5.ccls. and ((model\$4 simulat\$4) with (grid mesh element) )	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:57
L16	0	438/5.ccls. and ((model\$4 simulat\$4) with (grid mesh element) with (geometr\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:57
L15	281	438/5.ccls. and (model \$4 simulat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:56
L14	796	438/5.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:56

S160	0	703/7,13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (distributed adj simulat\$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:45
S159	0	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with ((plural\$4 many multipl) adj simulat\$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:44
S158	0	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (distributed adj simulat\$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:44
S157	0	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43
S156	0	703/13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43
S155	0	703/7.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43

S154	0	703/7.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))) .clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:42
S153	71	((ANDREJ) near2 (MITROVIC)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2011/05/06 10:07
S152	106	((ERIC) near2 (STRANG)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2011/05/06 10:06
S151	2	703/13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))) .clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 10:06
S150	7	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))) .clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 10:06
S149	83	S138 and S148	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32
S148	2807	700/121.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32
S147	234	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32

S146	41	700/29-31.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:31
S145	0	700/29-31.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:30
S144	0	"438"/\$.ccls. and (model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment) with (distributed adj simulat\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:27
S143	0	"438"/\$.ccls. and (model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment) with (code adj parallel\$8))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:27
S142	13	"438"/\$.ccls. and (model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment) with (grid geometr\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:26
S140	316	"438"/\$.ccls. and (model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:25
S139	13	S137 and S138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17

S138	2441	700/29-31.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17
S137	886	700/95.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17
S136	5	((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:10
S135	1	703/13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S134	0	703/7.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S133	0	703/13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S131	0	703/7.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:08

S129	2019	703/13.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:07
S128	2	"6802045".did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:58
S127	1404	703/22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:55
S126	55	(semiconductor near3 (process\$4 tool\$4 equipment manufactur \$4)) and ((model\$ simulat\$4) near5 ((physical geometry) near2 (machine tool manufactur\$4 assembly))) and ((parallel near3 process\$4) (code adj parallel\$8) ((plural distributed multiple) near4 simulat\$4) and grid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:49
S125	6	(semiconductor near3 (process\$4 tool\$4 equipment manufactur \$4)) and ((model\$ simulat\$4) near5 ((physical geometry) near2 (machine tool manufactur\$4 assembly))) and ((re adj (using use)) with (known start\$4 precomputed stor\$4) with (result solution output))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:42

S124	61	(semiconductor near3 (process\$4 tool\$4 equipment manufactur\$4)) and ((model\$ simulat\$4) near5 ((physical geometry) near2 (machine tool manufactur\$4 assembly))) and ((parallel near3 process\$4) (code adj parallel\$8) ((plural distributed multiple) near4 simulat\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:40
S123	314	(semiconductor near3 (process\$4 tool\$4 equipment manufactur\$4)) and ((model\$ simulat\$4) near5 ((physical geometry) near2 (machine tool manufactur\$4 assembly)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:38
S122	12	(semiconductor near3 (process\$4 tool\$4 equipment manufactur\$4)) with ((model\$ simulat\$4) near5 ((physical geometry) near2 (machine tool manufactur\$4 assembly)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:35
S121	2	"6615097".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:31
S120	4	US-20020032495-\$. DID. OR US-5719796-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:28

### EAST Search History (I nterference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp



L26	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (distributed adj simulat\$4)).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
L25	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
L24	0	438/5.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
S163	0	703/7.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:42
S162	1	703/13.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:39
S161	1	700/121.ccls. and ((model\$4 simulat\$4) with (semiconductor near2 (tool assembly manufactur\$4 equipment)) with (grid cell geometr\$4 (physical adj geometr\$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:39

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